

## **Advance Product Change Notification**

# 201504012A

Issue Date: 27-Apr-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



# QUALITY

#### Management Summary

Enable ASEN as a second source assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types

#### Change Category

[] Wafer Fab process

[] Wafer Fab materials

[] Assembly Materials [X] Assembly Location [] Wafer Fab location

[] Assembly Process

[] Product Marking [] Electrical spec./Test coverage [X] Test Location

[] Design

[] Mechanical Specification

[] Packing/Shipping/Labeling

# PL-HSI & MCU HVQFN32/HVQFN48 ASEN second source assembly & test

#### **Details of this Planned Change**

- Enable ASEN as an assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types.

- Assembly Material types and Test platforms will be the same

- NXP APK (the parent factory) provided loadboards for ATE use,

### Why do we Plan this Change

- The purpose is to expand our production capacity and to increase planning flexibility

### **Identification of Affected Products**

Top side marking

Top side marking with different marking code for new assembly center.

The marking of the assembly center is setup in the 3rd row where "X" indicates the assembly center ASEN.

## **Product Availability**

Sample Information Samples are available upon request Production

Planned first shipment 17-Jul-2015

Impact

no impact to the product's functionality anticipated.

No material changes or test platform changes will occur.

## **Disposition of Old Products**

Existing inventory will be shipped until depleted

## **Timing and Logistics**

The Self Qualification Report will be ready on 18-May-2015.

The Final PCN is planned to be issued on: 18-May-2015.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 27-May-2015.

#### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

 Name
 David Bannon

 Position
 Quality Manager BL SIP/PL-HSI

 e-mail address
 david.bannon@nxp.com

 At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

 Customer Focus, Passion to Win.

NXP Quality Management Team. About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	Support
NXP   Privacy Policy   Terms of Use		

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Customer Part#	Changed Part 12NC
PTN3361BBS,518	935287824518
PTN3360DBS,518	935291567518
LPC11U24FHI33/301,	935297186551
LPC11U35FHI33/501,	935297259551
PTN3363BSMP	935299074528
LPC822M101JHI33E	935304007551
LPC824M201JHI33E	935304008551
PTN3361BBS,518	935287824518
PTN3360DBS,518	935291567518
LPC11U35FHI33/501,	935297259551
PTN3363BSMP	935299074528
LPC822M101JHI33E	935304007551
LPC824M201JHI33E	935304008551